

Title (en)

PROCESS FOR PASSIVATING ANODIZATION OF COPPER IN A MOLTEN FLUORIDE MEDIUM, AND APPLICATION TO THE PROTECTION OF COPPER PARTS OF FLUORINE ELECTROLYZERS

Publication

**EP 0321536 B1 19930804 (FR)**

Application

**EP 88905883 A 19880623**

Priority

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Abstract (en)

[origin: WO8810328A1] In a process for obtaining a resistant, adherent, protective coating on copper parts with high recovery of substrate, by passivating anodization, said copper parts are immersed in a liquid KF, 2HF bath and subjected to a continuous or intermittent anodic current of low surface density less than 0.1 A/dm<sup>2</sup>.

IPC 1-7

**C25D 11/34**

IPC 8 full level

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